

Title (en)
ENCAPSULATION STRUCTURE FOR AN OPTO-ELECTRONIC COMPONENT, AND METHOD FOR ENCAPSULATING AN OPTOELECTRONIC COMPONENT

Title (de)
VERKAPSELUNGSSTRUKTUR FÜR EIN OPTOELEKTRONISCHES BAUELEMENT UND VERFAHREN ZUM VERKAPSELN EINES OPTOELEKTRONISCHEN BAUELEMENTES

Title (fr)
STRUCTURE D'ENCAPSULATION POUR COMPOSANT OPTOÉLECTRONIQUE ET PROCÉDÉ D'ENCAPSULATION D'UN COMPOSANT OPTOÉLECTRONIQUE

Publication
EP 2727164 A1 20140507 (DE)

Application
EP 12740316 A 20120620

Priority

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Abstract (en)
[origin: WO2013000797A1] An encapsulation structure (300) for an opto-electronic component (400) has the following: a thin-layer encapsulation (301) for protecting the opto-electronic component against chemical pollutants, an adhesive layer (302) produced on the thin-layer encapsulation and a top layer (303), produced on the adhesive layer, for protecting the thin-layer encapsulation and/or the opto-electronic component against mechanical damage.

IPC 8 full level
H10K 99/00 (2023.01); **H05B 33/04** (2006.01)

CPC (source: CN EP US)
H10K 50/844 (2023.02 - EP US); **H10K 30/88** (2023.02 - US); **H10K 50/84** (2023.02 - US); **H10K 50/841** (2023.02 - US); **H10K 50/8445** (2023.02 - CN EP US)

Citation (examination)

- WO 2009094997 A1 20090806 - OSRAM OPTO SEMICONDUCTORS GMBH [DE], et al
- US 2011100458 A1 20110505 - KANG JAE-WOOK [KR], et al
- US 2009195152 A1 20090806 - SAWANO MITSURU [JP]
- US 2005023974 A1 20050203 - CHWANG ANNA [US], et al
- See also references of WO 2013000797A1

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DOCDB simple family (publication)
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